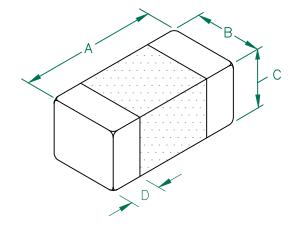
MI0603J102R-10

PHYSICAL DIMENSIONS:

A 1.60 [.063] ± 0.15 [.006] ± 0.15 [.006] B 0.80 [.031] [±] 0.15 [.006] C 0.80 [.031] D 0.36 [.014] ± 0.15 [.006]

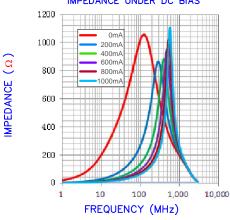


ELECTRICAL CHARACTERISTICS:										
Z @ 100MHz (<u>Ω</u>)		DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current							
Nominal	1000									
Minimum	750									
Maximum	1250	0.20	1000 mA							

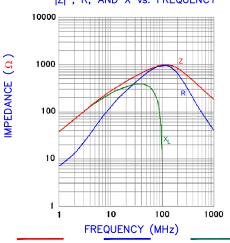
NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL. PAPER TAPE.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATING TEMP. RANGE: -55°C~+125°C (INCLUDING SELF-HEATING)

Z vs FREQUENCY IMPEDANCE UNDER DC BIAS



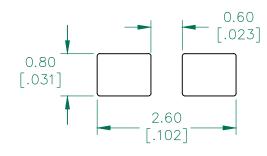
|Z| , R, AND X vs. FREQUENCY



AGILENT E4991A RF Impedance/Material Analyzer

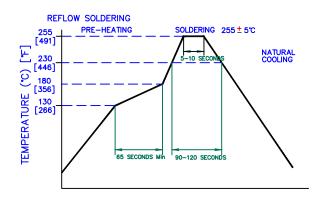
HP 16194A Test Fixture.

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS





	DIMENSIONS ARE IN mm [INCHE	ES]. This print is the property of Laird										
				Tech, and is loaned in confidence subject to return upon request an								
				with the understanding that no	ana	Laird						
				copies shall be made without the								
				written consent of Laird Tech. A rights to design or invention are								
				rights to design or invention are reserved.								
				PROJECT/PART NUMBER:		REV	PART 1	YPE:	DRAWN BY:			
				MI0603J102R-10		C	C CO-FIRE		QU			
O	UPDATE LAIRD LOGO AND NOTES 4	08/05/13	ਰ	WIIOOOSOTOZIX TO		_	"		w.c			
В	ADD DC BIAS CURVE	11/26/12	ď	DATE: 11/26/12	SCAL	E:		SHEET:				
Α	ORIGIINAL DRAFT	03/01/09	ą	O4D #	TOOL	-	-	2	of 2			
REV	DESCRIPTION	DATE	INT									